# **PNA1601M** (PN166)

### Silicon planar type

#### For optical control systems

#### Features

#### • High sensitivity

- Wide sspectral sensitivity characteristics, suited for detecting various kinds of LEDs
- Ultraminiature, thin side-view type package

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Collector current	I <sub>C</sub>	20	mA	
Collector power dissipation *	P <sub>C</sub>	50	mW	
Operating ambient temperature	T <sub>opr</sub>	-25 to +65	°C	
Storage temperature	T <sub>stg</sub>	-30 to +85	°C	

Note) \*: The rate of electric power reduction is 1.5 mW/°C above  $T_a = 25^{\circ}C$ .

#### Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Sensitivity to infrared radiation *1	S <sub>IR</sub>	$V_{CE} = 10 \text{ V}, \text{H} = 15 \ \mu\text{W/cm}^2$	3	5	25	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 10 V$			0.2	μΑ
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_{\rm C} = 10 \ \mu \text{A}, \text{H} = 15 \ \mu \text{W/cm}^2$			0.5	V
Peak sensitivity wavelength	$\lambda_{PD}$	$V_{CE} = 10 \text{ V}$		850		nm
Half-power angle	θ	The angle when the sensitivity to infrared radiation is halved		35		o
Rise time *2	t <sub>r</sub>	V = 10 V L = 5 m A R = 100 O		4		μs
Fall time *2	t <sub>f</sub>	$V_{\rm CC} = 10 \text{ V}, \text{ I}_{\rm C} = 5 \text{ mA}, \text{ R}_{\rm L} = 100 \Omega$		4		μs

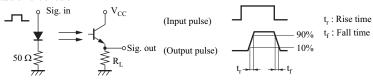
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.

3. This device is designed by disregarding radiation.

4. \*1:Source: Infrared radiation ( $\lambda = 940 \text{ nm}$ )

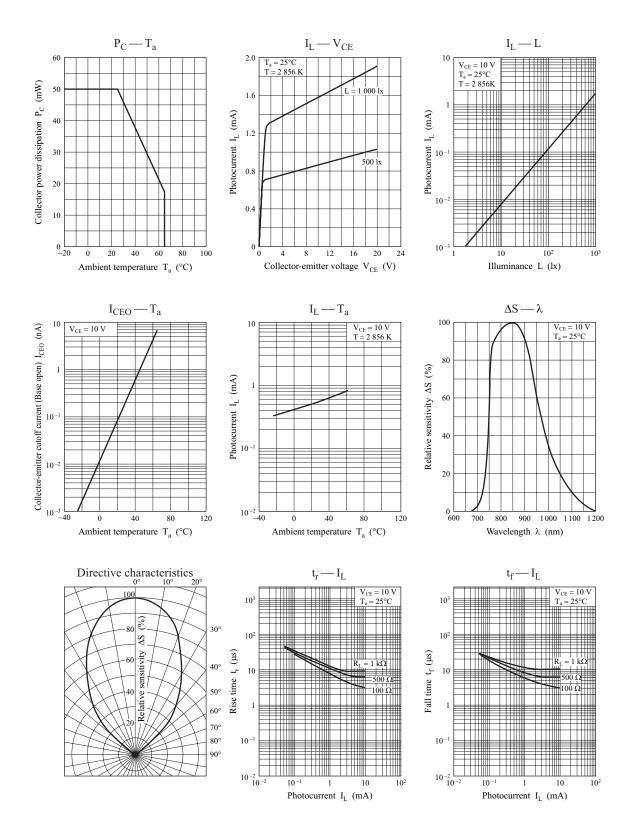
\*2: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.

#### PNA1601M

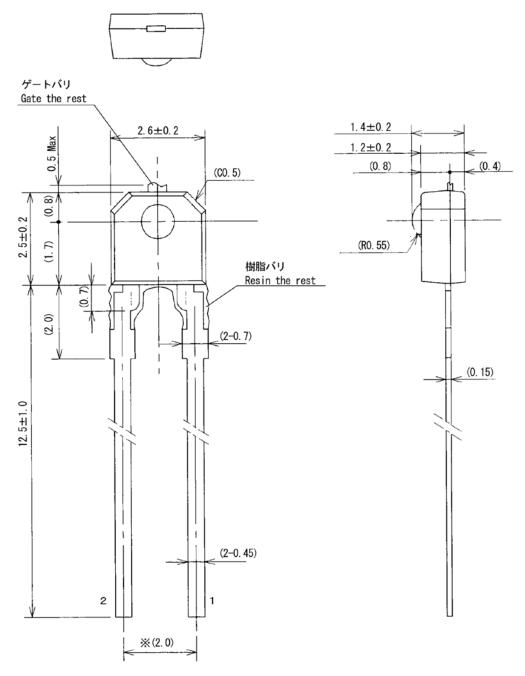
### **Panasonic**



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Package (Unit: mm)





(注 1)※リード根元寸法とする。/(Note1)※Indicates root dimensions of lead.

- Pin name
  - 1: Collector
  - 2: Emitter

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